TE Internal #: 2174988-1

TE Internal Description: SOCKET ASSY LGA2011-1, 0.38Au

LGA 2011 Sockets

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Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 2011 Sockets



IC Socket Type: LGA 2011

Number of Positions: 2011

Contact Mating Area Plating Material Thickness: [15 µin]

Centerline (Pitch): 1.02 mm [ .04 in ]

Termination Method to PCB: Surface Mount - Solder Ball

All LGA 2011 Sockets (0)

## **Features**

# **Product Type Features**

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Configuration Features	
Number of Positions	2011
Grid Spacing	1.016 x .8814 mm[.040 x .0347 in]
Body Features	
Frame Style	Square
Contact Features	
Contact Mating Area Plating Material	Gold (Au)
Contact Base Material	Copper Alloy
IC Socket Type	LGA 2011
	15 μin
Contact Current Rating (Max)	.5 A
Termination Features	

**Board Mount** 

**Mechanical Attachment** 

Connector Mounting Type



## **Housing Features**

Housing Color	Black	
Housing Material	High Temperature Thermoplastic	
Centerline (Pitch)	1.02 mm[.04 in]	
Operation/Application		

Circuit Application	Signal	

## **Industry Standards**

UL Flammability Rating	UL 94V-0	

## **Packaging Features**

Tray Color	Blue
Packaging Method	Tray

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2022 (223) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



# Customers Also Bought





















# **Documents**

## **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_2174988-1\_D.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2174988-1\_D.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2174988-1\_D.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

**Product Specifications** 

**Application Specification** 

Japanese



# TERMINATION OF AMP-LATCH ACTION PIN HEADER ASSEMBLY

Japanese